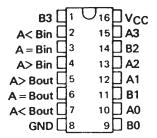
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	TYPICAL	TYPICAL
TYPE	POWER	DELAY
	DISSIPATION	(4-BIT WORDS)
'85	275 mW	23 ns
LS85	52 mW	24 ns
'S85	365 mW	11 ns

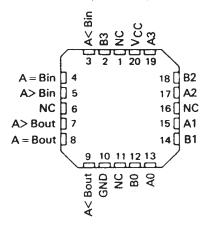
description

These four-bit magnitude comparators perform comparison of straight binary and straight BCD (8-4-2-1) codes. Three fully decoded decisions about two 4-bit words (A, B) are made and are externally available at three outputs. These devices are fully expandable to any number of bits without external gates. Words of greater length may be compared by connecting comparators in cascade. The A > B, A < B, and A = B outputs of a stage handling less-significant bits are connected to the corresponding A > B, A < B, and A = B inputs of the next stage handling more-significant bits. The stage handling the least-significant bits must have a high-level voltage applied to the A = B input. The cascading paths of the '85, 'LS85, and 'S85 are implemented with only a two-gate-level delay to reduce overall comparison times for long words. An alternate method of cascading which further reduces the comparison time is shown in the typical application data.

SN5485, SN54LS85, SN54S85 . . . J OR W PACKAGE SN7485 : . . N PACKAGE SN74LS85, SN74S85 . . . D OR N PACKAGE (TOP VIEW)



SN54LS85, SN54S85 . . . FK PACKAGE (TOP VIEW)



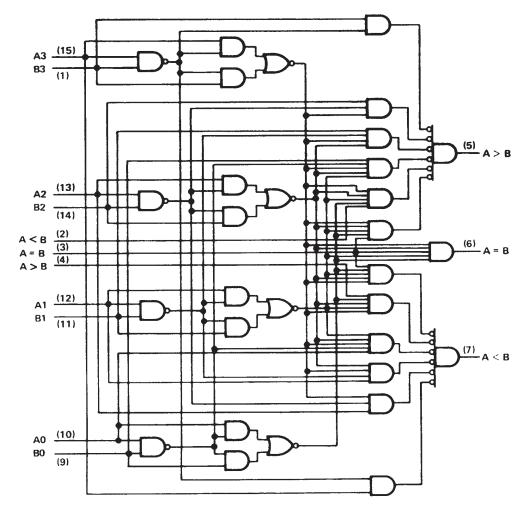
NC - No internal connection

FUNCTION TABLE

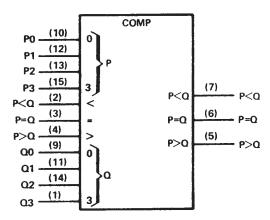
		ARING UTS			CASCADING OUTPUTS INPUTS				
A3, B3	A2, B2	A1, B1	A0, B0	A > B	A < B	A = B	A > B	A < B	A = 8
A3 > B3	X	×	×	Х	Х	Х	Н	L	L
A3 < B3	×	×	×	Х	×	X	L	Н	L
A3 = B3	A2 > B2	×	×	X	×	X	н	L	L
A3 = B3	A2 < B2	×	x	х	x	X	L	Н	L
A3 = B2	A2 = B2	A1 > B1	×	X	X	X	н	L	L
A3 = B3	A2 = B2	A1 < B1	×	Х	X	X	L	н	L
A2 = B3	A2 = B2	A1 = B1	A0 > B0	X	X	X	н	L	L
A3 = B3	A2 = B2	A1 = B1	A0 < 80	X	x	X	L	Н	L
A3 = B3	A2 = B2	A1 = B1	A0 = 80	н	L	L	Н	L	L
A3 = B3	A2 = B2	A1 = B1	AO = BO	L	н	L	L	Н	L
A3 = B3	A2 = B2	A1 = B1	A0 = B0	х	X	н	L	Ĺ	н
A3 = B3	A2 = B2	A1 = B1	AO = BO	н	н	Ł	L	L	L
A3 = B3	A2 = B2	A1 = B1	A0 = B0	L	L	L	н	н	L

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logic diagrams (positive logic)



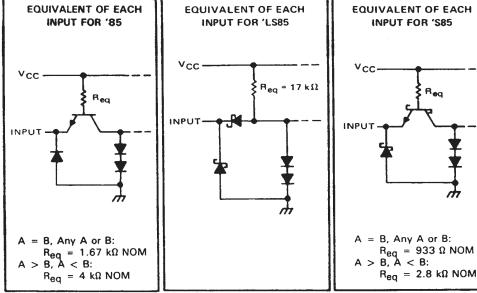
logic symbol†

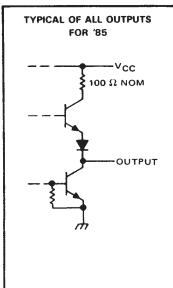


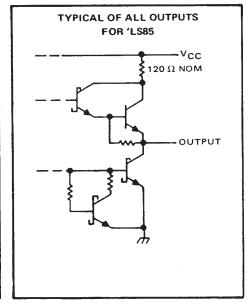
†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

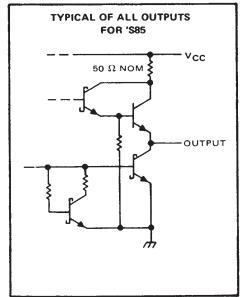


schematics of inputs and outputs









absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	SN54' SN54S'	SN54LS'	SN74' SN74S'	SN74LS'	UNIT
Supply voltage, V _{CC} (see Note 1)	7	7	7	7	V
Input voltage	5.5	7	5.5	7	V
Interemitter voltage (see Note 2)	5.5		5.5		V
Operating free-air temperature range	- 55	to 125	-0	to 70	°C
Storage temperature range	- 65	to 150	- 65	to 150	°C

NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.

2. This is the voltage between two emitters of a multiple-emitter input transistor. This rating applies to each A input in conjunction with its respective B input of the '85 and 'S85.



SN5485, SN54LS85, SN54S85 SN7485, SN74LS85, SN74S85 4-BIT MAGNITUDE COMPARATORS

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recommended operating conditions

		SN5485	5		SN7485	5	
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-400			-400	μА
Low-level output current, IOL			16			16	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TE	ST CONDIT	IONS†		MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage					-	2			V
VIL	Low-level input voltage								0.8	٧
VIK	Input clamp voltage	· · · ·	V _{CC} = MIN,		1 = -1	2 mA			-1.5	٧
Vон	High-level output voltage		V _{CC} = MIN, V _{IL} = 0.8 V,		V _{IH} = :	2 V, – 400 μΑ	2.4	3.4		٧
V _{OL}	Low-level output voltage		$V_{CC} = MIN,$ $V_{IL} = 0.8 \text{ V},$		V _{IH} = 1	2 V,		0.2	0.4	v
11	Input current at maximum in		V _{CC} = MAX,		V _I = 5.		 		1	mA
1	Mich found in much assessed	A < B, A > B inputs	V 440 V		14 - 2	41/			40	
ΉΗ	High-level input current	all other inputs	VCC = MAX,		V ₁ = 2.	4 V			120	μΑ
1	I am land to a summer	A < B, A > B inputs	V - MAY		· · · · ·	4.14			-1.6	
HL	Low-level input current	all other inputs	V _{CC} = MAX,		V _I = 0.	4 V			-4.8	mA
1	Character is a second	R	V	· · ·		SN5485	-20		-55	
los	Short-circuit output current	8	V _{CC} = MAX,	v0 = 0		SN7485	-18		-55	mΑ
1cc	Supply current		V _{CC} = MAX,	See Note 4	-			55	88	mA

 $^{^\}dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 4: I_{CC} is measured with outputs open, A = B grounded, and all other inputs at 4.5 V.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	FROM INPUT	TO OUTPUT	NUMBER OF GATE LEVELS	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		·	1			7		
	A A B -	A < B, $A > B$	2			12		
^t PLH	Any A or B data input		3]		17	26	ns
		A = B	A = B 4]		23	35	
			1	C _L = 15 pF,		11		
		A < B, A > B	2			15]
^t PH L	Any A or B data input	,	3	$R_1 = 400 \Omega$	20 20	20	30	ns
		A = B	4	See Note 5		30		
tPLH	A < B or A = B	A > B	1	See Note 5		7	11	ns
^t PHL	A < B or A = B	A > B	1	1		11	17	ns
t _{PLH}	A = 8	A = B	2			13	20	ns
^t PHL	A = B	A = B	2			11	17	ns
^t PLH	A > B or A = B	A < B	1			7	11	ns
^t PHL	A > B or A = B	A < B	1	1		11	17	пş

tpLH = propagation delay time, low-to-high-level output

NOTE 5: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}$ C.

[§]Not more than one output should be shorted at a time.

tpHL = propagation delay time, high-to-low-level output

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recommended operating conditions

	S	N54LS	35	S	N74LS	35	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-400			-400	μА
Low-level output current, IOL			4			8	mA
Operating free-air temperature, TA	-55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					S	N54LS8	15	S	N74LS8	15	
	PARAM	METER	TEST CON	IDITIONST	MIN	TYP‡	MAX	MIN	TYP [‡]	MAX	UNIT
VIH	High-level input	voltage			2			2			V
VIL	Low-level input						0.7			0.7	٧
VIK	Input clamp vol	tage	VCC = MIN,	I _I = -18 mA			-1.5			-1.5	٧
	III to to collect		V _{CC} = MIN,	V _{1H} = 2 V,	2.5	3.4		2.7	3.4		v
vон	High-level outpu	tvortage	V _I L = V _I L max,	$I_{OH} = -400 \mu\text{A}$	2.5	3.4		2.,	J.4		
			VCC = MIN,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	Low-level outpu	t voltage	V _{IH} = 2 V, V _{IL} = V _{IL} max	1 _{OL} = 8 mA					0.35	0.5	Ľ
	Input current	A < B, A > B inputs					0.1			0.1	
11	at maximum input voltage	all other inputs	V _{CC} = MAX,	V ₁ = 7 V			0.3			0.3	mA
	High-level	A < B, A > B inputs					20			20	μА
ΉН	input current	all other inputs	V _{CC} = MAX,	V ₁ = 2.7 V			60			60	J # ^
	Low-level	A < B, A > B inputs	1/ - MAY	V ₁ = 0.4 V			-0.4			-0.4	mA
HL	input current	all other inputs	V _{CC} = MAX,	V = 0.4 V			-1.2			-1.2	1
los	Short-circuit ou	tput current §	V _{CC} = MAX		-20		-100	-20		-100	mA
1cc	Supply current	-	VCC = MAX,	See Note 4		10.4	20		10.4	20	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 4: I_{CC} is measured with outputs open, A = B grounded, and all other inputs at 4.5 V.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

DADAMETED!	FROM	TO	NUMBER OF	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
PARAMETER¶	INPUT	OUTPUT	GATE LEVELS	TEST CONDITIONS					
			1			14		1	
		A < B, A > B	2		L	19		ns	
^t PLH	Any A or B data input		3			24	36] '''	
		A = B	4			27	45		
			1			11			
		A < B, A > B	A < B, A > B	2	0 15 5		15		ns
^t PHL	Any A or B data input		3	$C_L = 15 pF$		20	30] "	
		A = B	4	$R_L = 2 k\Omega$		23	45		
tPLH	A < B or A = B	A > B	1	See Note 5		14	22	ns	
tPHL	A < B or A = B	A > B	1	1		11	17	ns	
^t PLH	A = B	A = B	2			13	20	ns	
tPHL	A = B	A = B	2			13	26	ns	
tPLH	A > B or A = B	A < B	1	1		14	22	ns	
tPHL	A > B or A = B	A < B	1			11	17	ns	

 $[\]P_{tPLH}$ = propagation delay time, low-to-high-level output

NOTE 5: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C. \$Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

tpHL = propagation delay time, high-to-low-level output

SN5485, SN54LS85, SN54S85 SN7485, SN74LS85, SN74S85 4-BIT MAGNITUDE COMPARATORS

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recommended operating conditions

		SN54S8	5	SN74S85			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNII
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-1			-1	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETE	R	TES	T CONDITIONS	t	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage		"			2			٧
VIL.	Low-level input voltage							0.8	V
VIK	Input clamp voltage		VCC = MIN,	I ₁ = -18 mA				-1.2	V
			V _{CC} = MIN,	V _{IH} = 2 V,	SN54S85	2.5	3.4		V
v_{OH}	High-level output voltage		$V_{1L} = 0.8 V$	$I_{OH} = -1 \text{ mA}$	SN74S85	2.7	3.4		
			VCC = MIN,	V _{IH} = 2 V,				0.5	V
VOL	Low-level output voltage		VIL = 0.8 V,	1 _{OL} = 20 mA				0.5	1
11	Input current at maximum inp	ut voltage	VCC = MAX,	V ₁ = 5.5 V				1	mA
	11:11	A < B, A > B inputs	V _{CC} = MAX,	V 27 V				50	μА
HH	High-level input current	all other inputs	7 VCC - MAA,	V [= 2.7 V				150	1 40
		A < B, A > B inputs	VCC = MAX,	V. = 0 5 V				-2	mA
11L	Low-level input current	all other inputs	VCC = WAX,	V1 - 0.5 V				-6	11112
los	Short-circuit output current §		V _{CC} = MAX			-40		-100	mA
			V _{CC} = MAX,	See Note 4			73	115	
Icc	Supply current		V _{CC} = MAX, See Note 4	T _A = 125°C,	SN54S85W			110	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 4: I_{CC} is measured with outputs open, A = B grounded, and all other inputs at 4.5 V.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER¶	FROM INPUT	TO OUTPUT	NUMBER OF GATE LEVELS	TEST CONDITIONS	MIN TYP	MAX	UNIT	
			1		5		}	
		A < B, A > B	2		7.5		ns	
^t PLH	Any A or B data input		3		10.5	16] "	
		A = B	4		12	18		
			1			5.5		
		A < B, A > B	A < B, A > B	2	0 - 15 - 5	7		ns
^t PHL	Any A or B data input	•	3 1	C _L = 15 pF, R _L = 280 Ω, See Note 5	11	16.5	115	
		A = B	4		11	16.5		
tPLH	A < B or A = B	A > B	1		5	7.5	ns	
tPHL	A < B or A = B	A > B	1		5.5	8.5	ns	
tPLH	A = B	A = B	2		7	10.5	ns	
tPHL	A = B	A = B	2		5	7.5	ns	
tPLH	A > B or A = B	A < 8	1		5	7.5	ns	
tPHL	A > B or A = B	A < B	1		5.5	8.5	ns	

 $[\]P_{tpLH}$ = propagation delay time, low-to-high-level output

NOTE 5: Load circuits and voltage waveforms are shown in Section 1.

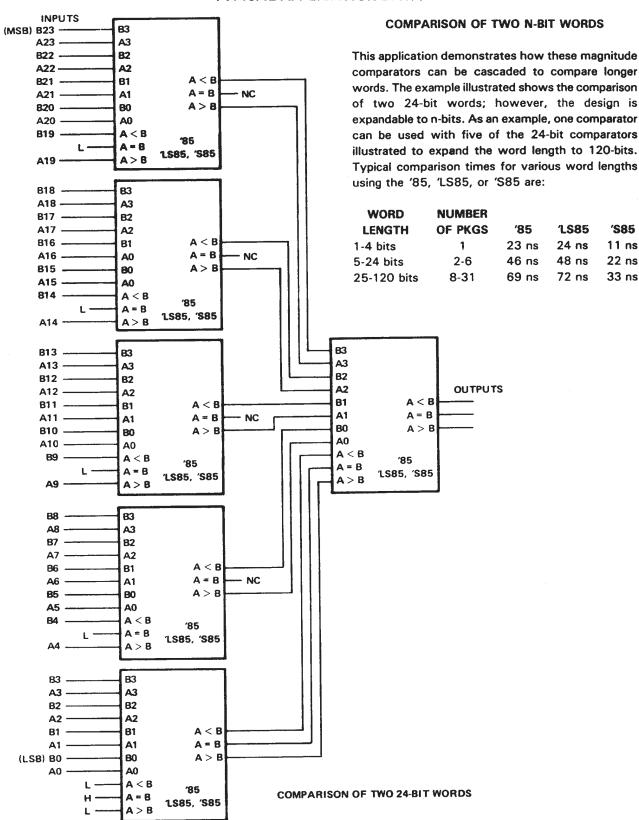


 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25^{\circ} \text{C}$.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

tpHL = propagation delay time, high-to-low-level output

TYPICAL APPLICATION DATA





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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9754701Q2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9754701Q2A SNJ54LS 85FK	Samples
5962-9754701QEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754701QE A SNJ54LS85J	Samples
5962-9754701QFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754701QF A SNJ54LS85W	Samples
JM38510/08201BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 08201BEA	Samples
JM38510/31101B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31101B2A	Samples
JM38510/31101BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31101BEA	Samples
JM38510/31101BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31101BFA	Samples
M38510/08201BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 08201BEA	Samples
M38510/31101B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31101B2A	Samples
M38510/31101BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31101BEA	Samples
M38510/31101BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31101BFA	Samples
SN54LS85J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS85J	Samples
SN54S85J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S85J	Samples
SN74LS85D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS85	Samples
SN74LS85DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS85	Samples



PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS85N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS85N	Samples
SN74LS85NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS85	Samples
SN74S85D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S85	Samples
SN74S85N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S85N	Samples
SNJ54LS85FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9754701Q2A SNJ54LS 85FK	Samples
SNJ54LS85J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754701QE A SNJ54LS85J	Samples
SNJ54LS85W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754701QF A SNJ54LS85W	Samples
SNJ54S85FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 85FK	Samples
SNJ54S85J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S85J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL. Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

PACKAGE OPTION ADDENDUM

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- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS85, SN54S85, SN74LS85, SN74S85:

Catalog: SN74LS85, SN74S85

Military: SN54LS85, SN54S85

NOTE: Qualified Version Definitions:

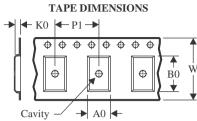
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

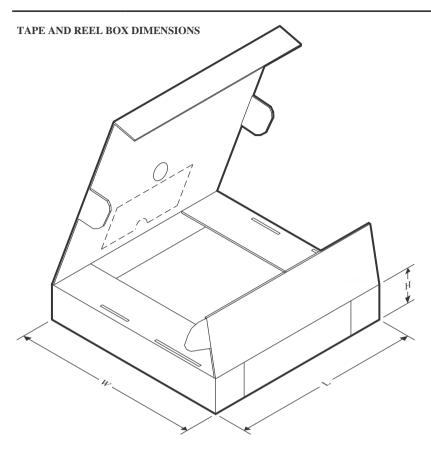


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS85DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS85NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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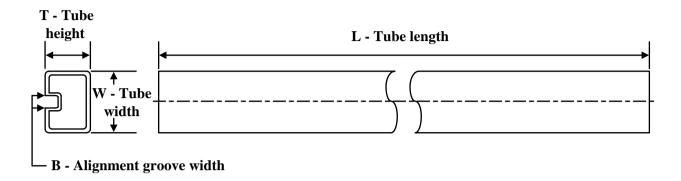
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS85DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS85NSR	SO	NS	16	2000	356.0	356.0	35.0



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9754701Q2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9754701QFA	W	CFP	16	1	506.98	26.16	6220	NA
JM38510/31101B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/31101BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/31101B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/31101BFA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS85D	D	SOIC	16	40	507	8	3940	4.32
SN74LS85N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS85N	N	PDIP	16	25	506	13.97	11230	4.32
SN74S85D	D	SOIC	16	40	507	8	3940	4.32
SN74S85N	N	PDIP	16	25	506	13.97	11230	4.32
SN74S85N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS85FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS85W	W	CFP	16	1	506.98	26.16	6220	NA
SNJ54S85FK	FK	LCCC	20	1	506.98	12.06	2030	NA

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

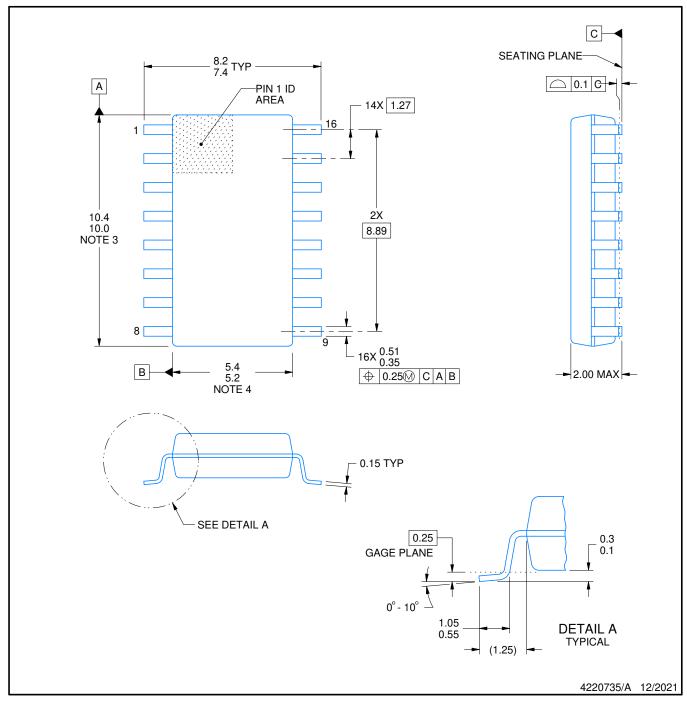


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



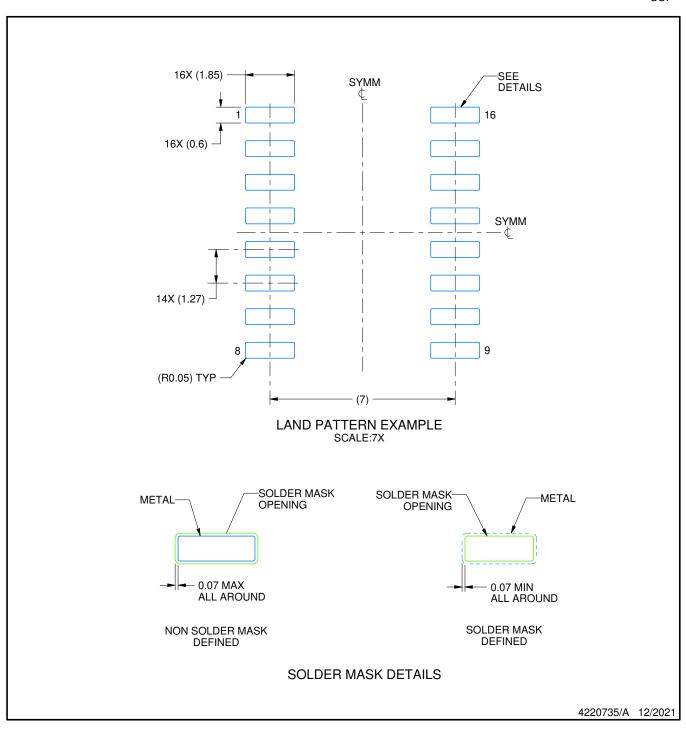
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



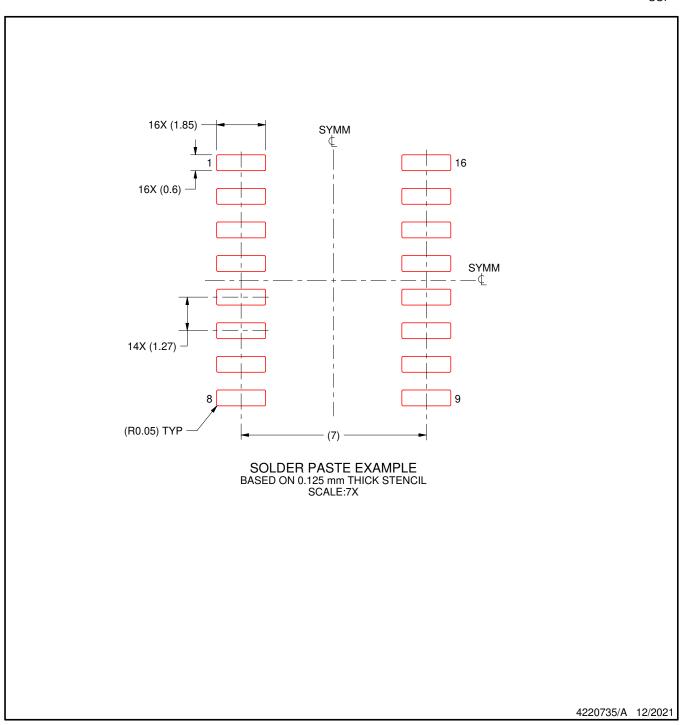
NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOP



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE

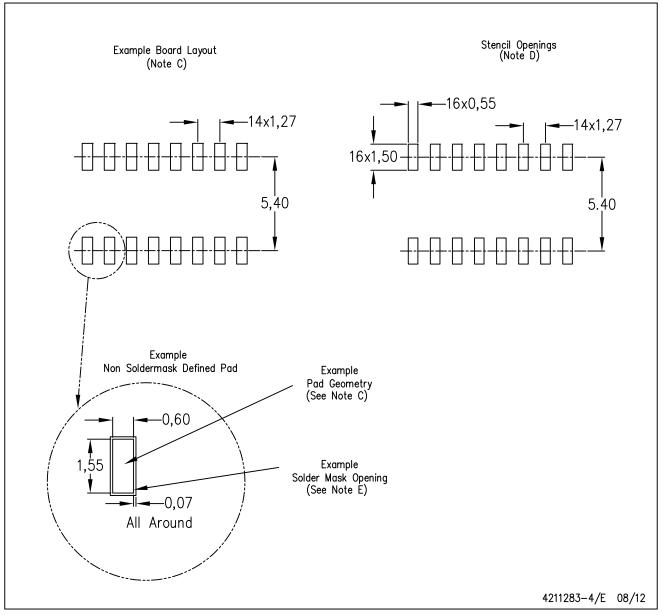


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE

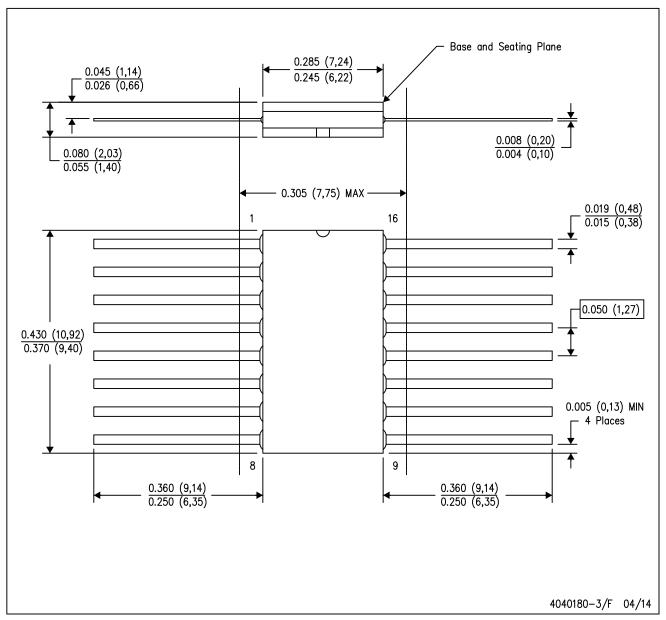


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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